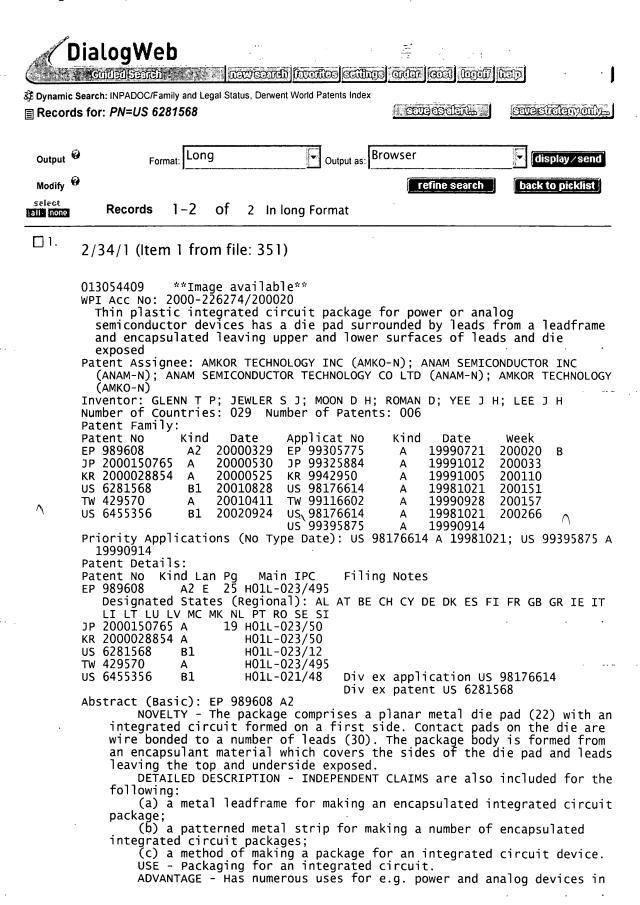
ſĹ.	Hits	Search Text	DB	Time stamp
Number	1.00005	(1) to 1/th man whith (nod moddle	USPAT;	2003/03/03
1	100205	(slot slit gap groove) with (pad paddle	US-PGPUB;	11:04
		heat)	EPO; JPO;	11.04
			DERWENT;	
			IBM TDB	
	205726	(pad paddle heat) with (opening slit slot	USPAT;	2003/03/03
2	285726	via grooves slots holes)	US-PGPUB;	11:05
		Via grooves stots notes;	EPO; JPO;	11.00
ļ			DERWENT;	
			IBM TDB	
3	35080	(semiconductor die chip ic (integrated	USPAT;	2003/03/03
	33000	adj circuit)) same ((pad paddle heat)	US-PGPUB;	11:07
		with (opening slit slot via grooves slots	EPO; JPO;	
		holes))	DERWENT;	
		110100//	IBM TDB	
4	204	((semiconductor die chip ic (integrated	USPAT;	2003/03/03
. 1	1	adj circuit)) same ((pad paddle heat)	US-PGPUB;	11:08
		with (opening slit slot via grooves slots	EPO; JPO;	
		holes))) same (tiebar dambar ((dam tie)	DERWENT;	
1		adj3 bar))	IBM_TDB	
5	171	(leadframe lead (lead adj frame)) same	USPAT;	2003/03/03
	!	(((semiconductor die chip ic (integrated	US-PGPUB;	11:09
		adj circuit)) same ((pad paddle heat)	EPO; JPO;	
		with (opening slit slot via grooves slots	DERWENT;	
		holes))) same (tiebar dambar ((dam tie)	IBM_TDB	
		adj3 bar)))		



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a small size package. Leads can be placed closer to the die to minimize the length of the bond wire. The exposed second surface of the die pad can be connected by solder to the printed circuit board for package cooling.

DESCRIPTION OF DRAWING(S) - The figure shows a plan view of the leadframe used for making the package.

Metal die pad (22)

Leads (30)

pp; 25 DwgNo 2/16

Derwent Class: U11

International Patent Class (Main): H01L-021/48; H01L-023/12; H01L-023/495; H01L-023/50

International Patent Class (Additional): H01L-023/28
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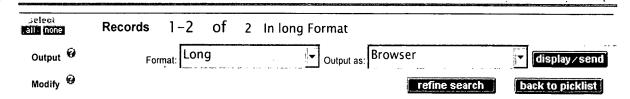
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□ 2.
        2/34/2
                    (Item 2 from file: 345)
       15806842
       Basic Patent (No, Kind, Date): EP 989608 A2 20000329
       PATENT FAMILY:
       EUROPEAN PATENT OFFICE (EP)
         Patent (No, Kind, Date): EP 989608 A2 20000329
           PLASTIC INTEGRATED CIRCUIT DEVICE PACKAGE AND METHOD OF MAKING THE SAME
             (English; French; German)
           Patent Assignee:
                                AMKOR TECHNOLOGY INC (US); ANAM SEMICONDUCTOR INC
             (KR)
                    (Inventor): GLENN THOMAS P (US); JEWLER SCOTT J (US); MOON D
           Author
           H (KR); ROMAN DAVID (US); YEE J H (KR)
Priority (No, Kind, Date): US 176614 A 19
                                                       19981021
           Applic (No, Kind, Date): EP 99305775 A
                                                      19990721
           Designated States: (National) AT; BE; CH; CY; DE; DK; ES; FI; FR; GB;
           GR; IE; IT; LI; LU; MC; NL; PT; SE IPC: * H01L-023/495
           Derwent WPI Acc No: * G 00-2
Language of Document: English
                                   G 00-226274; G 00-226274
         Patent (No, Kind, Date):
                                  EP 989608 A3 20010110
           PLASTIC INTEGRATED CIRCUIT DEVICE PACKAGE AND METHOD OF MAKING THE SAME
              (English; French; German)
           Patent Assignee:
                                AMKOR TECHNOLOGY INC (US); ANAM SEMICONDUCTOR INC
             (KR)
                    (Inventor): GLENN THOMAS P (US); JEWLER SCOTT J (US); MOON D
           Author
             H (KR); ROMAN DAVID (US); YEE J H (KR)
           Priority (No, Kind, Date): US 176614 A
                                                       19981021
           Applic (No, Kind, Date): EP 99305775 A
                                                      19990721
           Designated States: (National) AT; BE; CH; CY; DE; DK; ES; FI; FR; GB;
           GR; IE; IT; LI; LU; MC; NL; PT; SE IPC: * H01L-023/495
           Derwent WPI Acc No: *
                                   G 00-226274
           Language of Document: English
       JAPAN (JP)
         Patent (No, Kind, Date): JP 2000150765 A2 20000530
           SEMICONDUCTOR INTEGRATED CIRCUIT PLASTIC PACKAGE, ULTRA- COMPACT LEAD
             FRAME FOR MANUFACTURE THEREOF, AND ITS MANUFACTURE (English)
           Patent Assignee: AMKOR TECHNOLOGY INC; ANAM SEMICONDUCTOR INC
           Author
                   (Inventor): GLENN THOMAS P; JEWLER SCOTT J; ROMAN DAVID; YEE J
             H; D H MUN
           Priority (No, Kind, Date): US 176614 A
                                                       19981021
           Applic (No, Kind, Date): JP 99325884 A
                                                       19991012
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H01L-023/50; H01L-023/12; H01L-023/28

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Derwent WPI Acc No: * G 00-226274
    Language of Document: Japanese
KOREA, REPUBLIC (KR)
  Patent (No, Kind, Date): KR 2000028854 A
                                                       20000525
     PLASTIC INTEGRATED CIRCUIT DEVICE PACKAGE, MICRO LEAD FRAME AND
       PRODUCING METHOD OF PACKAGE (English)
     Patent Assignee: AMKOR TECHNOLOGY KOREA INC; AMKOR ELECTRONICS INC
    Author (Inventor): GLEN THOMAS P (KR); JEWELLER SCOTT J (KR); ROMAN
               (KR); LEE JAE HAK (KR); MUN DU WHAN (KR)
       DAVID
     Priority (No, Kind, Date): US 176614 A
                                                     19981021
    Applic (No, Kind, Date): KR 9942950 A IPC: * H01L-023/50
                                                      19991005
     Derwent WPI Acc No: * G 00-226274
     Language of Document: Korean
UNITED STATES OF AMERICA (US)
Patent (No,Kind,Date): US 6281568 BA 20010828
     PLASTIC INTEGRATED CIRCUIT DEVICE PACKAGE AND LEADFRAME HAVING
       PARTIALLY UNDERCUT LEADS AND DIE PAD (English)
     Patent Assignee: AMKOR TECHNOLOGY INC (US); ANAM SEMICONDUCTOR INC
       (US)
     Author (Inventor): GLENN THOMAS P (US); JEWLER SCOTT J (US): ROMAN
    DAVID (US); YEE J H (KR); MOON D H (KR)
Priority (No, Kind, Date): US 176614 A 19981021
Applic (No, Kind, Date): US 176614 A 19981021
National Class: * 257675000; 257698000; 257698000;
       257796000; 257675000; 257712000; 257713000; 257707000; 257711000:
       257730000; 257788000
    IPC: * H01L-023/12; H01L-023/28; H01L-023/50 Derwent WPI Acc No: * G 00-226274 Language of Document: English
  Patent (No, Kind, Date): US 6455356 BA 20020924
     METHODS FOR MODING A LEADFRAME IN PLASTIC INTEGRATED CIRCUIT DEVICES
       (English)
    Patent Assignee: AMKOR TECHNOLOGY (US)
Author (Inventor): GLENN THOMAS P (US); JEWLER SCOTT J (US); ROMAN
DAVID (US); YEE J H (KR); MOON D H (KR)
Priority (No, Kind, Date): US 395875 A 19990914; ÛS 176614 A3
       19981021
     Applic (No, Kind, Date): US 395875 A
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       029841000; 029855000
     IPC: * H01L-021/48
    Derwent WPI Acc No: * G 00-226274
     Language of Document: English
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